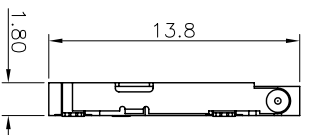
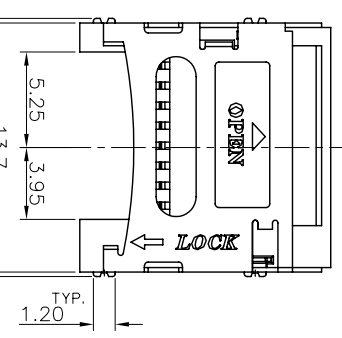
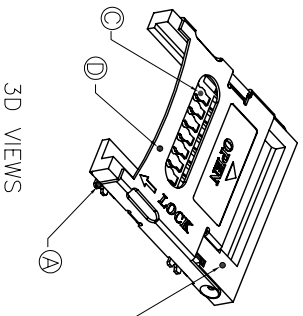


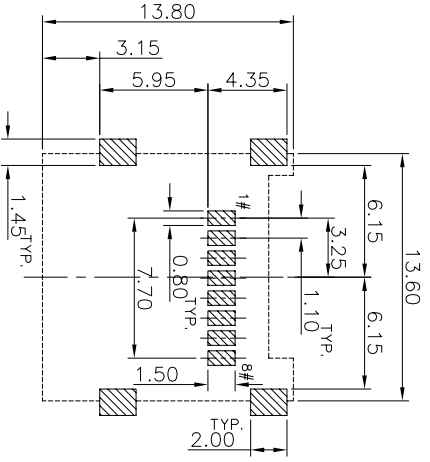
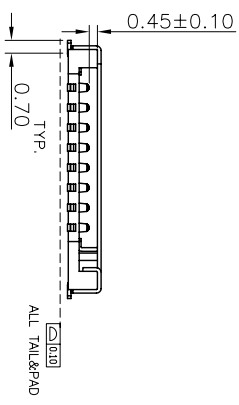
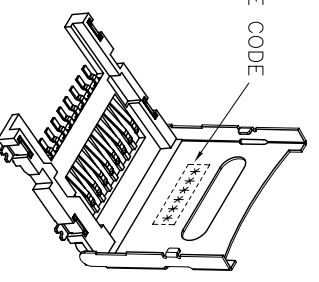
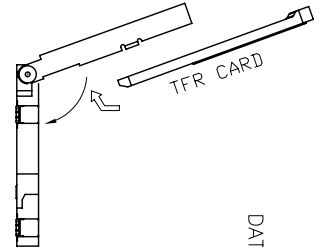
REV. A	ECN NO. OR DESCRIPTION	REVISED	DATE
	INITIAL RELEASE	劉木達	4/5/06



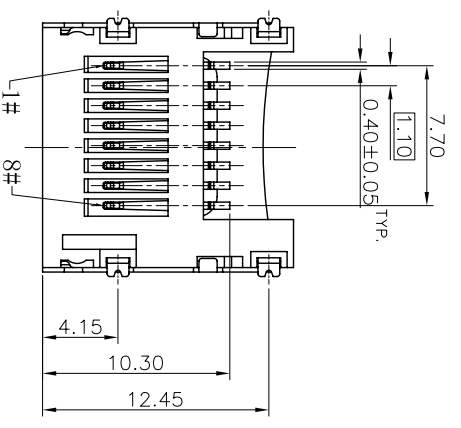
SHELL LOCK



3D VIEWS



RECOMMENDED PCB PATTERN LAYOUT  
TOLERANCE: ±0.05



Pin No.	Name	Type	DESCRIPTION
1	DAT2	I/O/PP	Data Line [bit2]
2	CD/DAT3	I/O/PP	Card Detect Data Line [bit3]
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DATO	I/O/PP	Data Line [bit0]
8	DAT1	I/O/PP	Data Line [bit1]

D	Shell	1	STAINLESS STEEL	/
C	Contact	8	COPPER ALLOY	SEE TABLE
B	Housing	1	HIGH TEMP. THERMOPLASTIC	(UL94-V0) BLACK
A	Sold Pin	4	COPPER ALLOY	Sn:100u"min Ni:50u"min PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS: ANGLES:				
X :±0.5 X :±2°				
X.X :±0.3 X.X :±1°				
X.XX :±0.2 X.XX				
TITLE TRANS FLASH HIGNE TYPE I				
DWG 劉木達 4/5/06 PART NO. 2CA-0006-000				
CHKD SCALE:N/A UNIT: mm				
APVD SEAN 4/5/06 SIZE: A3 SHEET:10F 1 REV:A				
CUSTOMER COPY				

- NOTES:
- MATERIAL :  
HOUSING:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0,BLACK  
SHELL:STAINLESS STEEL.  
CONTACT:COPPER ALLOY.  
DETECT PIN: COPPER ALLOY.
  - PLATING:  
CONTACT  
a: 20u" Min. Au PLATING IN CONTACT AREA;  
100u"Min. Sn PLEATED OVERALL,  
50u" Min. Ni UNDERPLATED OVERALL.  
b: GOLD FLASH PLATING ON CONTACT OVERALL  
50u" Min. Ni UNDERPLATED OVERALL.  
PAD:100u" Min. Sn PLATING OVER ALL  
50u"Min. Ni UNDERPLATED OVERALL .  
3.ELECTRICAL CHARACTERISTIC:  
CONNECT RESISTANCE:80 MILLIONMS/PIN Max.  
INSULATION RESISTANCE:1000 MEGAOHMS Min.  
VOLTAGE WITHSTAND:500V AC for 1minute
  - DATE CODE: \*\*\*\*\*  
Day  
Month  
Year

2CA-0006-002 G/F(b)

2CA-0006-001 Au 20u"(c)

P/N. CONTACT PLATING

Form: 2 1 2 3 4 5 6 7 8